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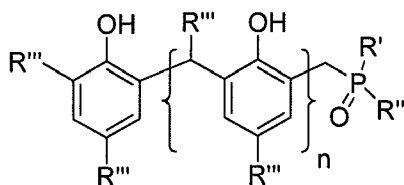
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(54) Title: DIMETHYLFORMAMIDE-FREE FORMULATIONS USING DICYNADIAMIDE AS CURING AGENT FOR THERMOSETTING EPOXY RESINS



(57) Abstract: Substantially homogeneous solutions including dicyandi- amide and phenolic hardeners having the general formula; where R' and R'' may be the same or different and each represents R- or RO- radicals, with R being an alkyl or aromatic radical; R''' is hydrogen, an alkyl or aromatic radical, -CH₂P(O)RR'', or -CH₂OR; n is a whole number within the range from 0 to 100. Also disclosed are curable compositions including an epoxy resin and the above-described phenolic hardener solution and processes for making the same.

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